



Material Content Data Sheet



Sales Product Name	TLE8108EM			Issued	28. August 2013			
MA#	MA000969214							
Package	PG-SSOP-24-4			Weight*	150.68 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.956	1.96	1.96	19618	19618
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		112	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8927	
wire	non noble metal	copper	7440-50-8	54.617	36.25	37.19	362461	371946
	noble metal	gold	7440-57-5	0.629	0.42	0.42	4173	4173
	encapsulation	organic material	carbon black	1333-86-4	0.174	0.12		1155
encapsulation	plastics	epoxy resin	-	8.003	5.31		53111	
	inorganic material	silicondioxide	60676-86-0	78.811	52.30	57.73	523024	577290
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19318	19318
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1555	1555
glue	plastics	epoxy resin	-	0.230	0.15		1525	
	noble metal	silver	7440-22-4	0.689	0.46	0.61	4575	6100
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

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